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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	26
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc982fdh-529

4. Block diagram

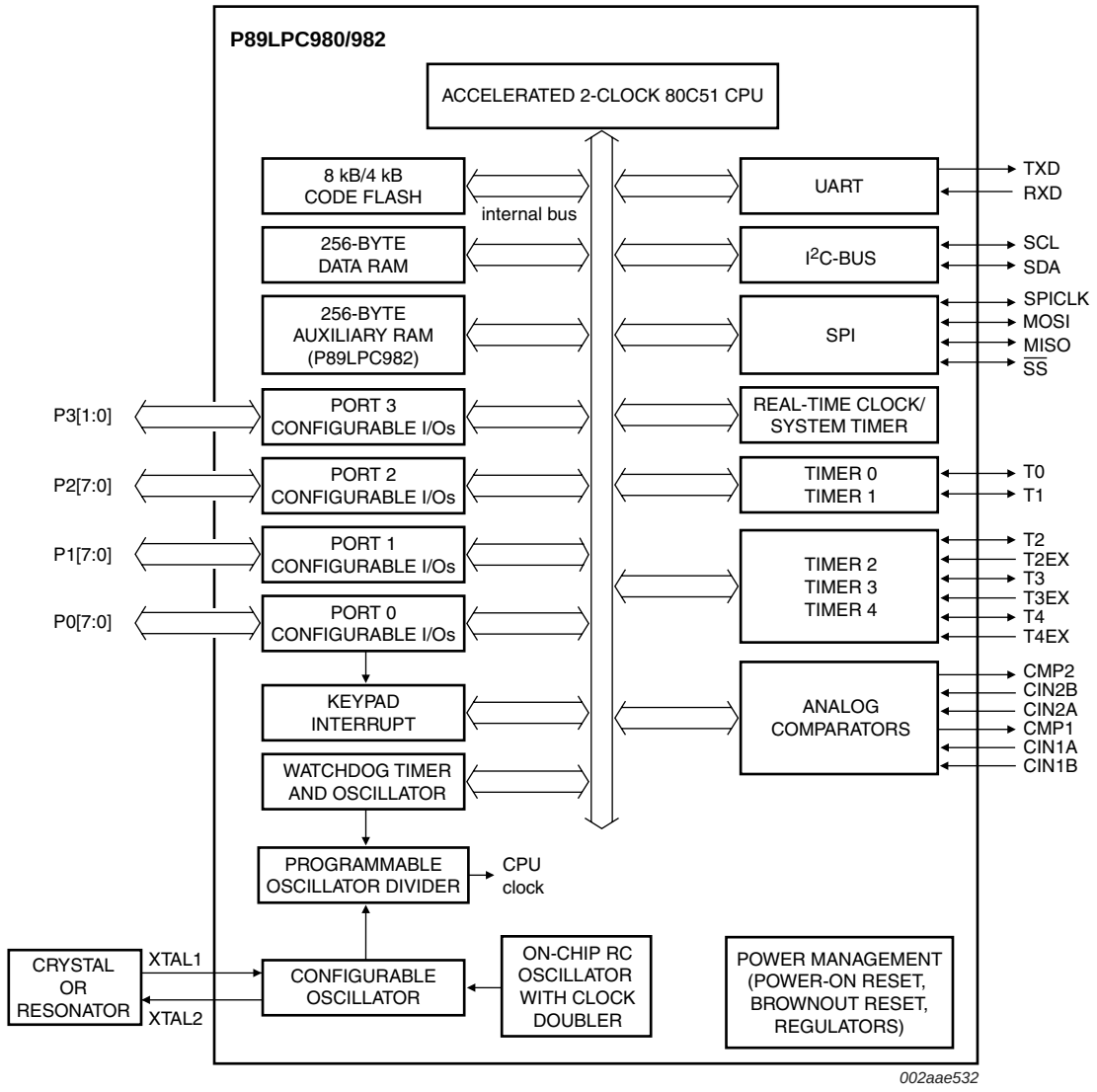
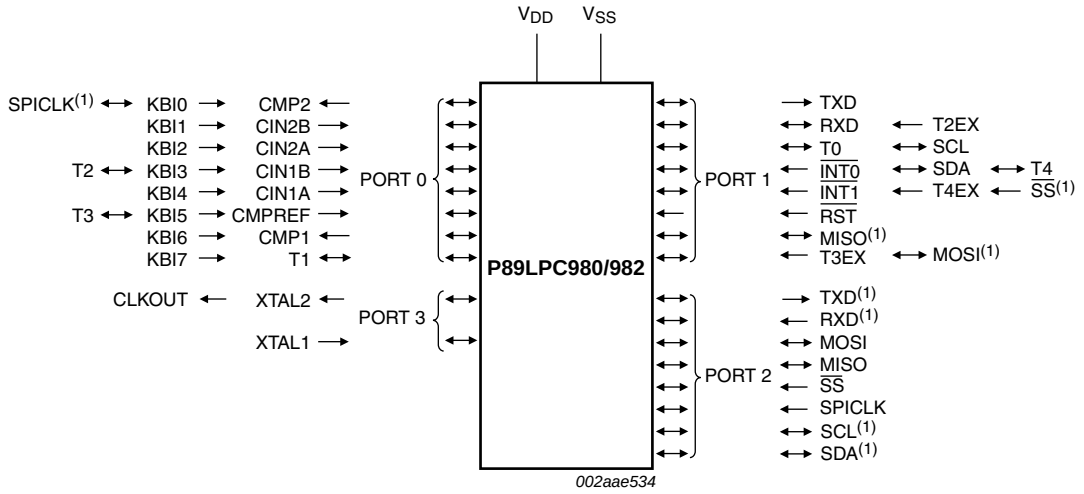


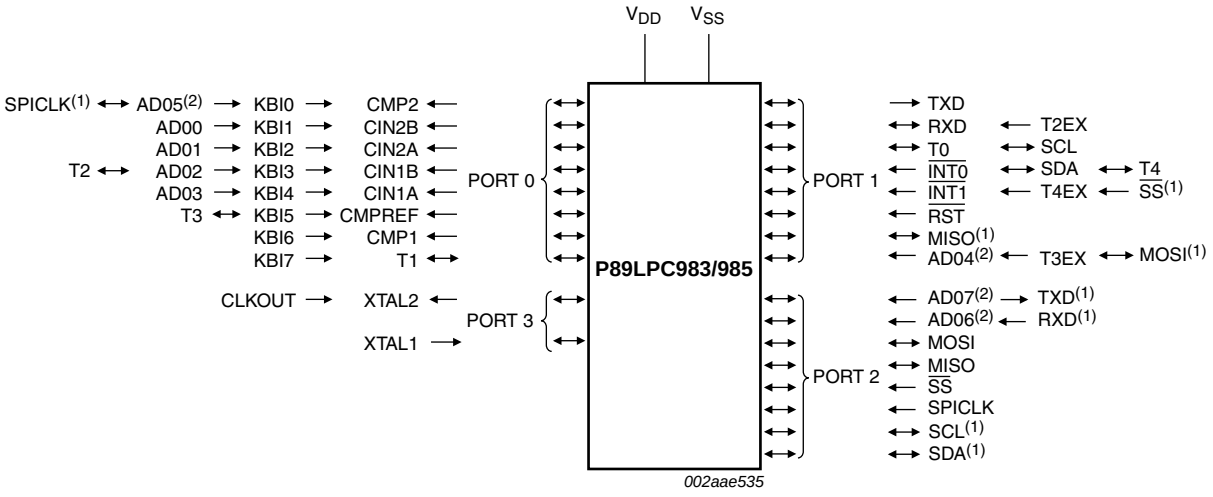
Fig 1. P89LPC980/982 block diagram

5. Functional diagram



(1) For pin remap

Fig 3. P89LPC980/982 Functional diagram



(1) For pin remap

(2) Only on the P89LPC985

Fig 4. P89LPC983/985 Functional diagram

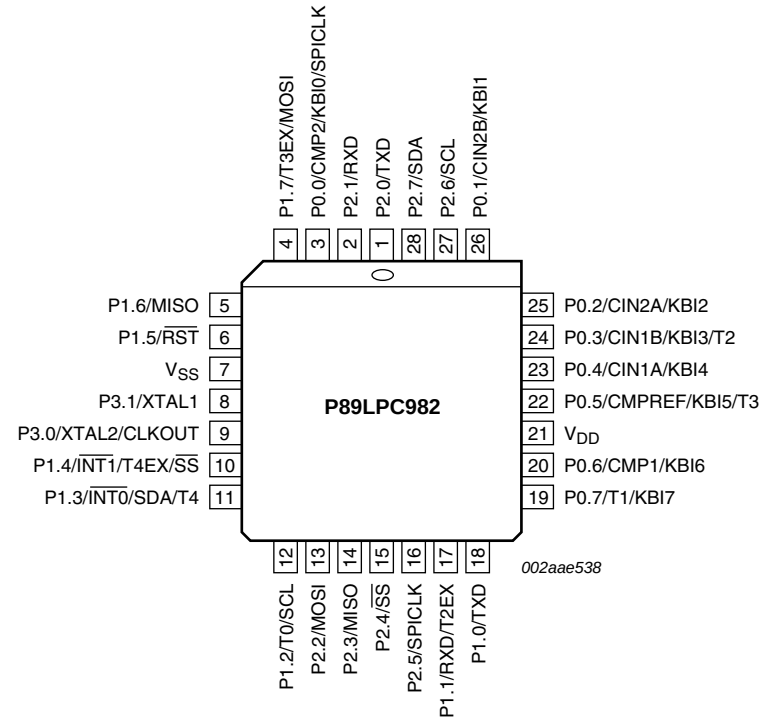


Fig 7. P89LPC982 PLCC28 pin configuration

Table 3. Pin description *…continued*

Symbol	Pin	Type	Description
	PLCC28, TSSOP28		
P3.0/XTAL2/ CLKOUT	9	I/O	**P3.0 —** Port 3 bit 0.
		O	**XTAL2 —** Output from the oscillator amplifier (when a crystal oscillator option is selected via the flash configuration.
		O	**CLKOUT —** CPU clock divided by 2 when enabled via SFR bit (ENCLK -TRIM.6). It can be used if the CPU clock is the internal RC oscillator, watchdog oscillator or external clock input, except when XTAL1/XTAL2 are used to generate clock source for the RTC/system timer.
P3.1/XTAL1	8	I/O	**P3.1 —** Port 3 bit 1.
		I	**XTAL1 —** Input to the oscillator circuit and internal clock generator circuits (when selected via the flash configuration). It can be a port pin if internal RC oscillator or watchdog oscillator is used as the CPU clock source, **and** if XTAL1/XTAL2 are not used to generate the clock for the RTC/system timer.
V_{SS}	7	I	**Ground:** 0 V reference.
V_{DD}	21	I	**Power supply:** This is the power supply voltage for normal operation as well as Idle and Power-down modes.

[1] Input/output for P1.0 to P1.4, P1.6, P1.7. Input for P1.5.

Table 4. Special function registers - P89LPC980/982 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
SPCTL	SPI control register	E2H	SSIG	SPEN	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04	0000 0100
SPSTAT	SPI status register	E1H	SPIF	WCOL	-	-	-	-	-	-	00	00xx xxxx
SPDAT	SPI data register	E3H									00	0000 0000
TAMOD	Timer 0 and 1 auxiliary mode	8FH	-	-	-	T1M2	-	-	-	T0M2	00	xxx0 xxx0
	Bit address		**8F**	**8E**	**8D**	**8C**	**8B**	**8A**	**89**	**88**		
TCON*	Timer 0 and 1 control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00	0000 0000
TH0	Timer 0 high	8CH									00	0000 0000
TH1	Timer 1 high	8DH									00	0000 0000
TL0	Timer 0 low	8AH									00	0000 0000
TL1	Timer 1 low	8BH									00	0000 0000
TMOD	Timer 0 and 1 mode	89H	T1GATE	T1C/T	T1M1	T1M0	T0GATE	T0C/T	T0M1	T0M0	00	0000 0000
T2CON	Timer/Counter 2 Control	FFH	PSEL2	ENT2	TIEN2	PWM2	EXEN2	TR2	C/NT2	CP/NRL2	00	0000 0000
TH2	Timer/Counter 2 High Byte	FEH									00	0000 0000
TL2	Timer/Counter 2 Low Byte	FDH									00	0000 0000
T3CON	Timer/Counter 3 Control	EFH	PSEL3	ENT3	TIEN3	PWM3	EXEN3	TR3	C/NT3	CP/NRL3	00	0000 0000
TH3	Timer/Counter 3 High Byte	EEH									00	0000 0000
TL3	Timer/Counter 3 Low Byte	EDH									00	0000 0000
T4CON	Timer/Counter 2 Control	CDH	PSEL4	ENT4	TIEN4	PWM4	EXEN4	TR4	C/NT4	CP/NRL4	00	0000 0000
TH4	Timer/Counter 4 High Byte	CCH									00	0000 0000

Table 4. Special function registers - P89LPC980/982 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
TL4	Timer/Counter 4 Low Byte	CBH									00	0000 0000
TINTF	Timer/Counters 2/3/4 Overflow and External Flags	CEH	-	-	TF4	EXF4	TF3	EXF3	TF2	EXF2	00	0000 0000
TRIM	Internal oscillator trim register	96H	RCCLK	ENCLK	TRIM.5	TRIM.4	TRIM.3	TRIM.2	TRIM.1	TRIM.0	[4][5]	
WDCON	Watchdog control register	A7H	PRE2	PRE1	PRE0	-	-	WDRUN	WDTOF	WDCLK	[4][6]	
WDL	Watchdog load	C1H									FF	1111 1111
WFEED1	Watchdog feed 1	C2H										
WFEED2	Watchdog feed 2	C3H										

[1] BRGR1 and BRGR0 must only be written if BRGEN in BRGCON SFR is logic 0. If any are written while BRGEN = 1, the result is unpredictable.

[2] All ports are in input only (high-impedance) state after power-up.

[3] The RSTSRC register reflects the cause of the P89LPC980/982/983/985 reset except BOIF bit. Upon a power-up reset, all reset source flags are cleared except POF and BOF; the power-on reset value is x011 0000.

[4] The only reset sources that affect these SFRs are power-on reset and watchdog reset.

[5] On power-on reset and watchdog reset, the TRIM SFR is initialized with a factory preprogrammed value. Other resets will not cause initialization of the TRIM register.

[6] After reset, the value is 1110 01x1, i.e., PRE2 to PRE0 are all logic 1, WDRUN = 1 and WDCLK = 1. WDTOF bit is logic 1 after watchdog reset and is logic 0 after power-on reset. Other resets will not affect WDTOF.

Table 6. Special function registers - P89LPC983/985

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
	Bit address		E7	E6	E5	E4	E3	E2	E1	E0		
ACC*	Accumulator	E0H									00	0000 0000
AD0CON	A/D control register 0	97H	ENBI0	ENADCI0	TMM10	EDGE0	ADCI0	ENADC0	ADCS01	ADCS00	00	0000 0000
AD0INS	A/D input select	A3H	AIN07	AIN06	AIN05	AIN04	AIN03	AIN02	AIN01	AIN00	00	0000 0000
AD0MODA	A/D mode register A	C0H	BNDI0	BURST0	SCC0	SCAN0	-	-	-	-	00	0000 0000
AD0MODB	A/D mode register B	A1H	CLK2	CLK1	CLK0	INBND0	-	-	BSA0	FCIIS	00	000x 0000
AUXR1	Auxiliary function register	A2H	CLKLP	EBRR	ENT1	ENT0	SRST	0	-	DPS	00	0000 00x0
	Bit address		F7	F6	F5	F4	F3	F2	F1	F0		
B*	B register	F0H									00	0000 0000
BRGR0[1]	Baud rate generator 0 rate low	BEH									00	0000 0000
BRGR1[1]	Baud rate generator 0 rate high	BFH									00	0000 0000
BRGCON	Baud rate generator 0 control	BDH	-	-	-	-	-	-	SBRGS	BRGEN	00[1]	xxxx xx00
CMP1	Comparator 1 control register	ACH	-	-	CE1	CP1	CN1	OE1	CO1	CMF1	00[2]	xx00 0000
CMP2	Comparator 2 control register	ADH	-	-	CE2	CP2	CN2	OE2	CO2	CMF2	00[2]	xx00 0000
DIVM	CPU clock divide-by-M control	95H									00	0000 0000
DPTR	Data pointer (2 bytes)											
DPH	Data pointer high	83H									00	0000 0000

Table 7. Extended special function registers - P89LPC983/985[1]

Name	Description	SFR addr.	Bit functions and addresses		Reset value	
			MSB	LSB	Hex	Binary
AD0DAT0L	ADC0 data register 0, left (MSB)	FFFFH	AD0DAT0 [9:2]		00	0000 0000
AD0DAT0R	ADC0 data register 0, right (LSB)	FFFEH	AD0DAT0 [7:0]		00	0000 0000
AD0DAT1L	ADC0 data register 1, left (MSB)	FFFDH	AD0DAT1 [9:2]		00	0000 0000
AD0DAT1R	ADC0 data register 1, right (LSB)	FFFCH	AD0DAT1 [7:0]		00	0000 0000
AD0DAT2L	ADC0 data register 2, left (MSB)	FFFBH	AD0DAT2 [9:2]		00	0000 0000
AD0DAT2R	ADC0 data register 2, right (LSB)	FFFAH	AD0DAT2 [7:0]		00	0000 0000
AD0DAT3L	ADC0 data register 3, left (MSB)	FFF9H	AD0DAT3 [9:2]		00	0000 0000
AD0DAT3R	ADC0 data register 3, right (LSB)	FFF8H	AD0DAT3 [7:0]		00	0000 0000
AD0DAT4L	ADC0 data register 4, left (MSB)	FFF7H	AD0DAT4 [9:2]		00	0000 0000
AD0DAT4R	ADC0 data register 4, right (LSB)	FFF6H	AD0DAT4 [7:0]		00	0000 0000
AD0DAT5L	ADC0 data register 5, left (MSB)	FFF5H	AD0DAT5 [9:2]		00	0000 0000
AD0DAT5R	ADC0 data register 5, right (LSB)	FFF4H	AD0DAT5 [7:0]		00	0000 0000

Each interrupt source can be individually programmed to one of four priority levels by setting or clearing bits in the interrupt priority registers IP0, IP0H, IP1 and IP1H. An interrupt service routine in progress can be interrupted by a higher priority interrupt, but not by another interrupt of the same or lower priority. The highest priority interrupt service cannot be interrupted by any other interrupt source. If two requests of different priority levels are pending at the start of an instruction, the request of higher priority level is serviced.

If requests of the same priority level are pending at the start of an instruction, an internal polling sequence determines which request is serviced. This is called the arbitration ranking. Note that the arbitration ranking is only used to resolve pending requests of the same priority level.

7.15.1 External interrupt inputs

The P89LPC980/982/983/985 has two external interrupt inputs as well as the Keypad Interrupt function. The two interrupt inputs are identical to those present on the standard 80C51 microcontrollers.

These external interrupts can be programmed to be level-triggered or edge-triggered by setting or clearing bit IT1 or IT0 in Register TCON.

In edge-triggered mode, if successive samples of the $\overline{\text{INTn}}$ pin show a HIGH in one cycle and a LOW in the next cycle, the interrupt request flag IEn in TCON is set, causing an interrupt request.

If an external interrupt is enabled when the P89LPC980/982/983/985 is put into Power-down or Idle mode, the interrupt will cause the processor to wake-up and resume operation. Refer to Section 7.17.3 “Power reduction modes” for details.

7.16.1.3 Input-only configuration

The input-only port configuration has no output drivers. It is a Schmitt trigger input that also has a glitch suppression circuit.

7.16.1.4 Push-pull output configuration

The push-pull output configuration has the same pull-down structure as both the open-drain and the quasi-bidirectional output modes, but provides a continuous strong pull-up when the port latch contains a logic 1. The push-pull mode may be used when more source current is needed from a port output. A push-pull port pin has a Schmitt triggered input that also has a glitch suppression circuit. The P89LPC980/982/983/985 device has high current source on eight pins in push-pull mode. See Table 12 “Limiting values”.

7.16.2 Port 0 analog functions

The P89LPC980/982/983/985 incorporates two Analog Comparators. In order to give the best analog function performance and to minimize power consumption, pins that are being used for analog functions must have the digital outputs and digital inputs disabled.

Digital outputs are disabled by putting the port output into the Input-Only (high-impedance) mode.

Digital inputs on Port 0 may be disabled through the use of the PT0AD register, bits 1:5. On any reset, PT0AD[1:5] defaults to logic 0s to enable digital functions.

7.16.3 Additional port features

After power-up, all pins are in Input-Only mode. **Please note that this is different from the LPC76x series of devices.**

- After power-up, all I/O pins except P1.5, may be configured by software.
- Pin P1.5 is input only. Pins P1.2 and P1.3 are configurable for either input-only or open-drain.

Every output on the P89LPC980/982/983/985 has been designed to sink typical LED drive current. However, there is a maximum total output current for all ports which must not be exceeded. Please refer to Table 13 “Static characteristics” for detailed specifications.

All ports pins that can function as an output have slew rate controlled outputs to limit noise generated by quickly switching output signals. The slew rate is factory-set to approximately 10 ns rise and fall times.

7.16.4 Pin remap

This feature allows the functions of UART/I2C/SPI to be remapped to other pins. Configuration register controls the multiplexers to allow connection between the pins and the on chip peripherals. See Table 10 “SPI/I2C/UART pin remap”.

UART/I2C/SPI, each has two options of pin configuration: primary pin map and alternative pin map. After reset, UART/I2C/SPI chooses the primary pin map as default. User can adjust to the alternative pin map through configuring PINCON register according to the application.

automatic address recognition, selectable double buffering and several interrupt options. The UART can be operated in four modes: shift register, 8-bit UART, 9-bit UART, and CPU clock/32 or CPU clock/16.

7.22.1 Mode 0

Serial data enters and exits through RXD. TXD outputs the shift clock. 8 bits are transmitted or received, LSB first. The baud rate is fixed at $1/16$ of the CPU clock frequency.

7.22.2 Mode 1

10 bits are transmitted (through TXD) or received (through RXD): a start bit (logic 0), 8 data bits (LSB first), and a stop bit (logic 1). When data is received, the stop bit is stored in RB8 in special function register SCON. The baud rate is variable and is determined by the Timer 1 overflow rate or the baud rate generator (described in Section 7.22.5 “Baud rate generator and selection”).

7.22.3 Mode 2

11 bits are transmitted (through TXD) or received (through RXD): start bit (logic 0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (logic 1). When data is transmitted, the 9th data bit (TB8 in SCON) can be assigned the value of logic 0 or logic 1. Or, for example, the parity bit (P, in the PSW) could be moved into TB8. When data is received, the 9th data bit goes into RB8 in special function register SCON, while the stop bit is not saved. The baud rate is programmable to either $1/16$ or $1/32$ of the CPU clock frequency, as determined by the SMOD1 bit in PCON.

7.22.4 Mode 3

11 bits are transmitted (through TXD) or received (through RXD): a start bit (logic 0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (logic 1). In fact, Mode 3 is the same as Mode 2 in all respects except baud rate. The baud rate in Mode 3 is variable and is determined by the Timer 1 overflow rate or the baud rate generator (described in Section 7.22.5 “Baud rate generator and selection”).

7.22.5 Baud rate generator and selection

The P89LPC980/982/983/985 enhanced UART has an independent baud rate generator. The baud rate is determined by a baud-rate preprogrammed into the BRGR1 and BRGR0 SFRs which together form a 16-bit baud rate divisor value that works in a similar manner as Timer 1 but is much more accurate. If the baud rate generator is used, Timer 1 can be used for other timing functions.

The UART can use either Timer 1 or the baud rate generator output (see Figure 11). Note that Timer T1 is further divided by 2 if the SMOD1 bit (PCON.7) is cleared. The independent baud rate generators use OSCCLK.

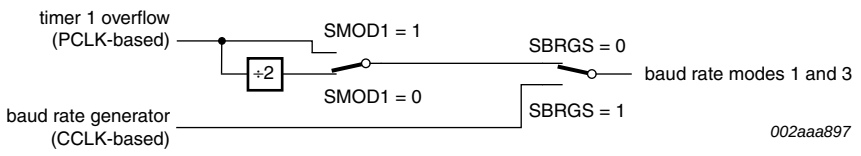


Fig 11. Baud rate sources for UART (Modes 1, 3)

- The I²C-bus may be used for test and diagnostic purposes.

A typical I²C-bus configuration is shown in Figure 12. The P89LPC980/982/983/985 device provides a byte-oriented I²C-bus interface that supports data transfers up to 400 kHz.

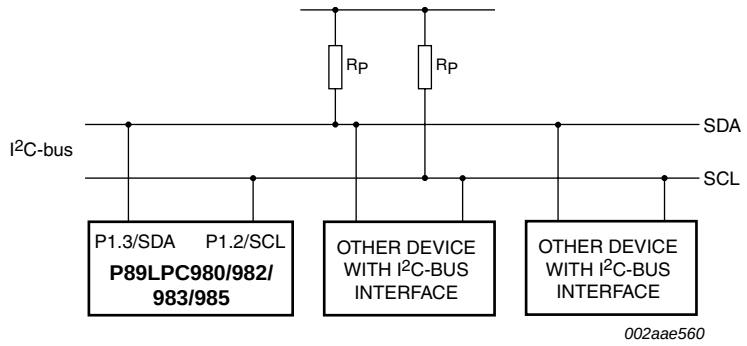


Fig 12. I²C-bus configuration

7.24.1 Typical SPI configurations

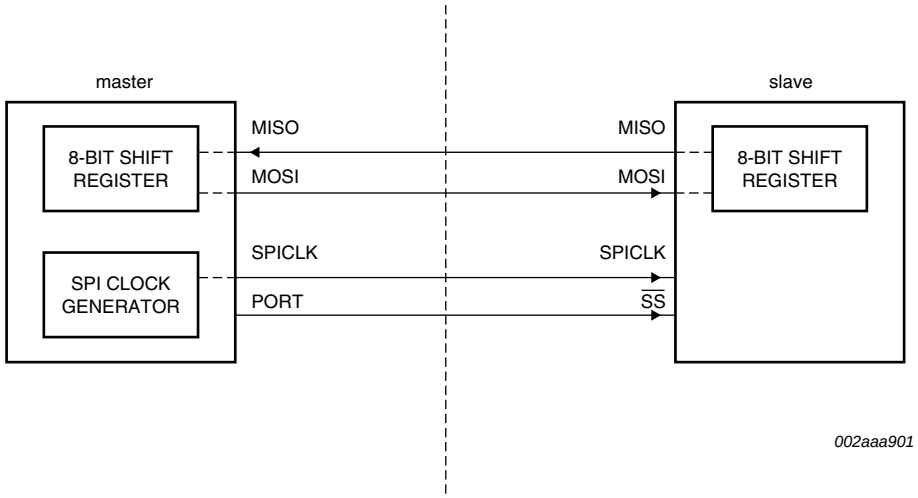


Fig 15. SPI single master single slave configuration

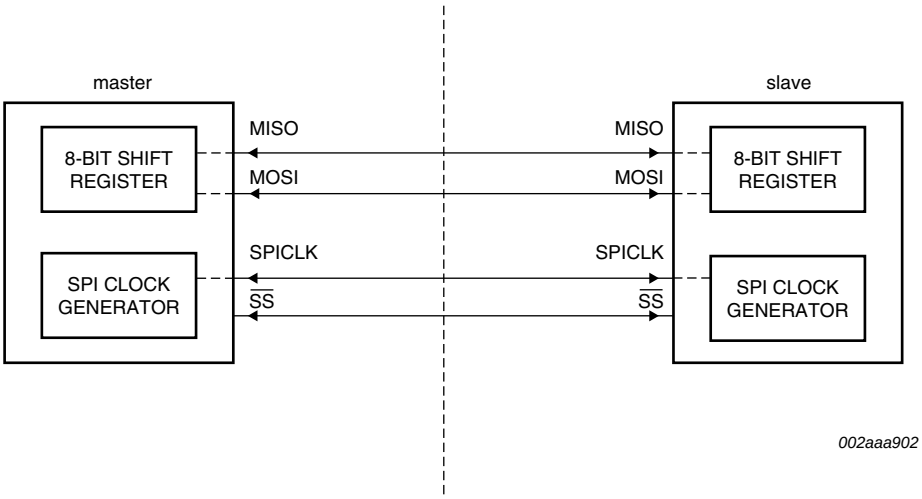
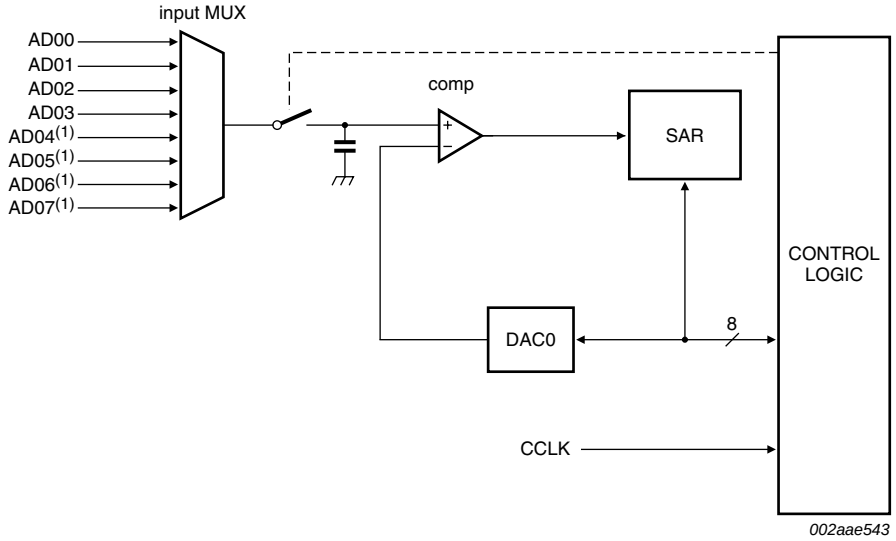


Fig 16. SPI dual device configuration, where either can be a master or a slave

8.3 Block diagram



(1) Only on the P89LPC985.

Fig 20. ADC block diagram

8.4 ADC operating modes

8.4.1 Fixed channel, single conversion mode

A single input channel can be selected for conversion. A single conversion will be performed and the result placed in the result register pair which corresponds to the selected input channel. An interrupt, if enabled, will be generated after the conversion completes.

8.4.2 Fixed channel, continuous conversion mode

A single input channel can be selected for continuous conversion. The results of the conversions will be sequentially placed in the eight result register. The user may select whether an interrupt can be generated after every four or every eight conversions. Additional conversion results will again cycle through the result register pairs, overwriting the previous results. Continuous conversions continue until terminated by the user.

8.4.3 Auto scan, single conversion mode

Any combination of the eight input channels can be selected for conversion. A single conversion of each selected input will be performed and the result placed in the result register pair which corresponds to the selected input channel. The user may select whether an interrupt, if enabled, will be generated after either the first four conversions have occurred or all selected channels have been converted. If the user selects to generate an interrupt after the four input channels have been converted, a second interrupt will be generated after the remaining input channels have been converted. If only a single channel is selected this is equivalent to single channel, single conversion mode.

Table 15. Dynamic characteristics (18 MHz) *…continued*
V_{DD} = 3.6 V to 5.5 V unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 18 MHz		Unit
			Min	Max	Min	Max	
$t_{SPILEAD}$	SPI enable lead time	see Figure 26, 27					
	slave		250	-	250	-	ns
t_{SPILAG}	SPI enable lag time	see Figure 26, 27					
	slave		250	-	250	-	ns
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 24, 25, 26, 27					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 24, 25, 26, 27					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 24, 25, 26, 27					
	master or slave		100	-	100	-	ns
t_{SPIDH}	SPI data hold time	see Figure 24, 25, 26, 27					
	master or slave		100	-	100	-	ns
t_{SPIA}	SPI access time	see Figure 26, 27					
	slave		0	80	0	80	ns
t_{SPIDIS}	SPI disable time	see Figure 26, 27					
	slave		0	160	-	160	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 24, 25, 26, 27					
	slave		-	160	-	160	ns
	master		-	111	-	111	ns
t_{SPIOH}	SPI output data hold time	see Figure 24, 25, 26, 27	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 24, 25, 26, 27					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 24, 25, 26, 27					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

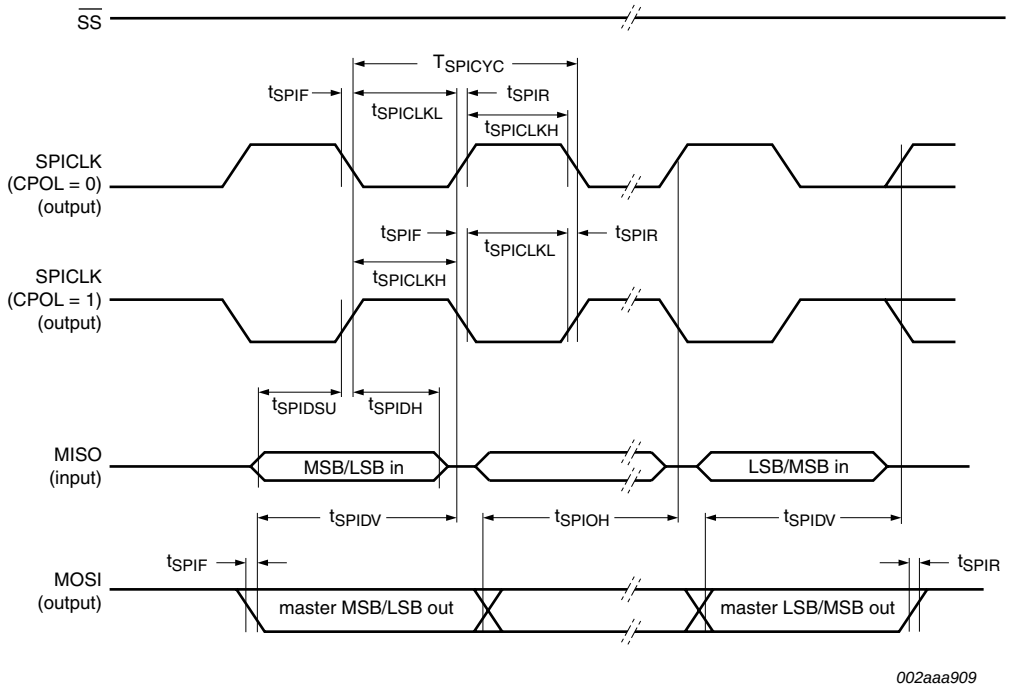


Fig 25. SPI master timing (CPHA = 1)

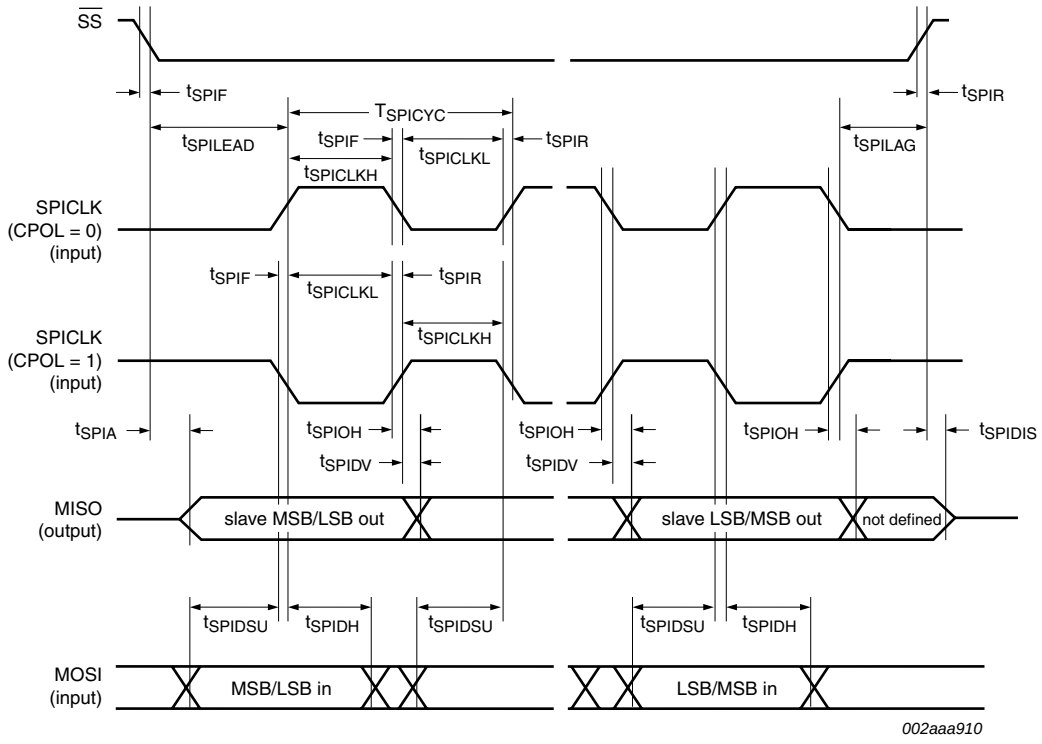


Fig 26. SPI slave timing (CPHA = 0)

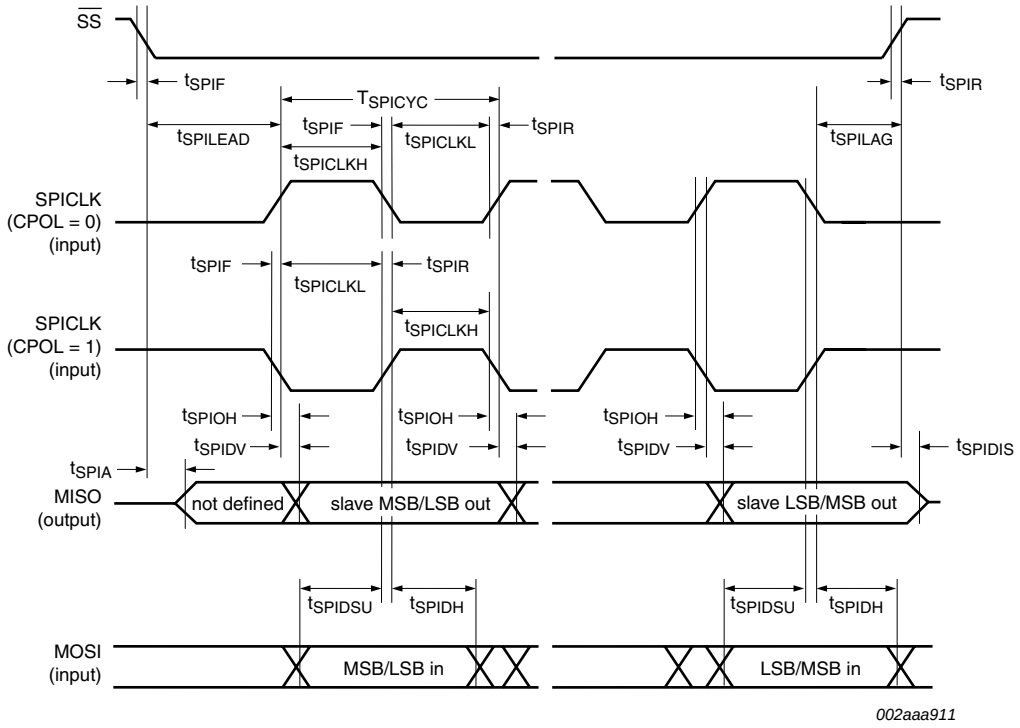


Fig 27. SPI slave timing (CPHA = 1)

11.2 ISP entry mode

Table 16. Dynamic characteristics, ISP entry mode

V_{DD} = 2.4 V to 5.5 V, unless otherwise specified.
T_{amb} = −40 °C to +85 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{VR}	V_{DD} active to $\overline{RST}$ active delay time	pin P1.5/$\overline{RST}$	50	-	-	µs
t_{RH}	$\overline{RST}$ HIGH time	pin P1.5/$\overline{RST}$	1	-	32	µs
t_{RL}	$\overline{RST}$ LOW time	pin P1.5/$\overline{RST}$	1	-	-	µs

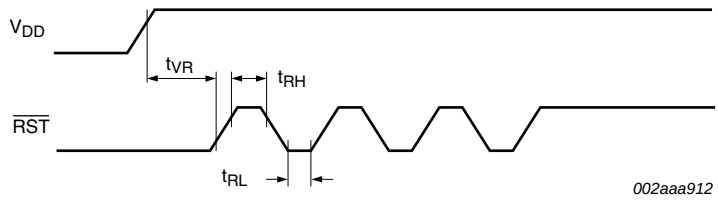
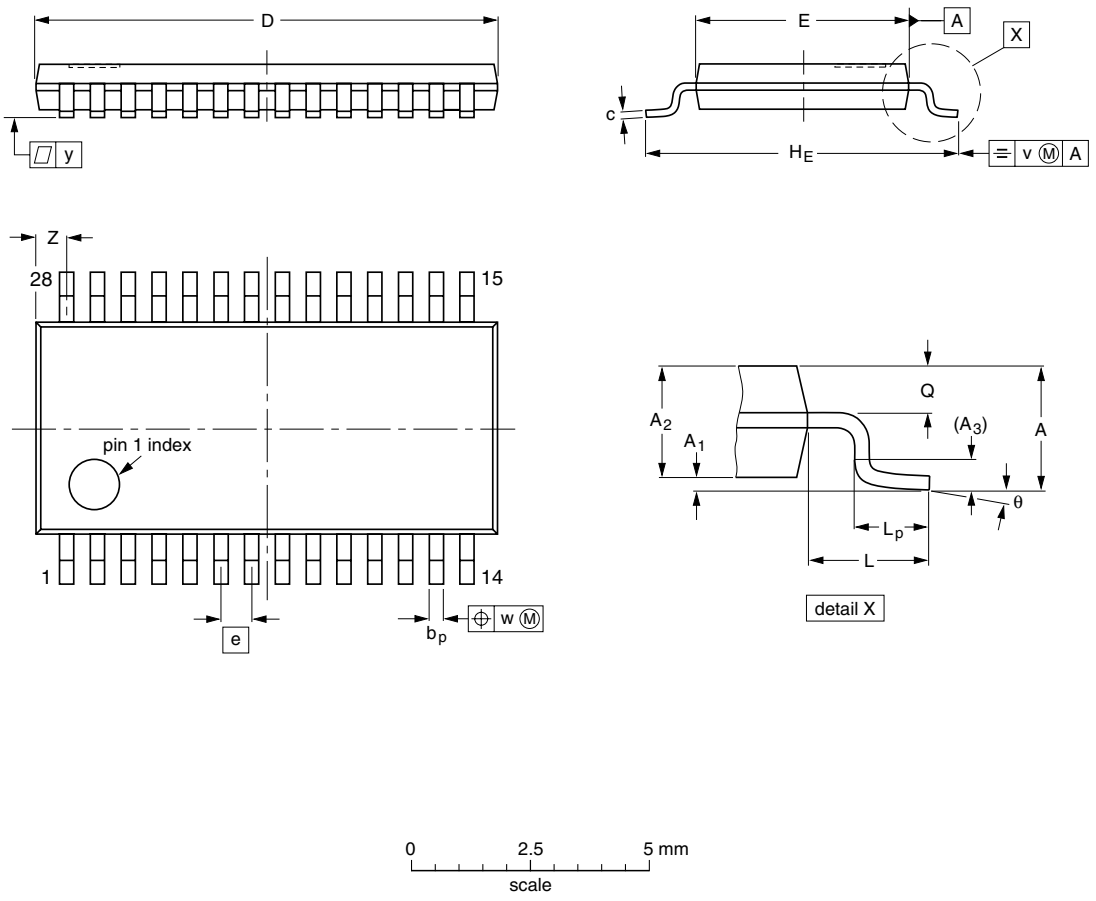


Fig 28. ISP entry waveform

13. Package outline

TSSOP28: plastic thin shrink small outline package; 28 leads; body width 4.4 mm **SOT361-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	9.8 9.6	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.8 0.5	8^o 0^o

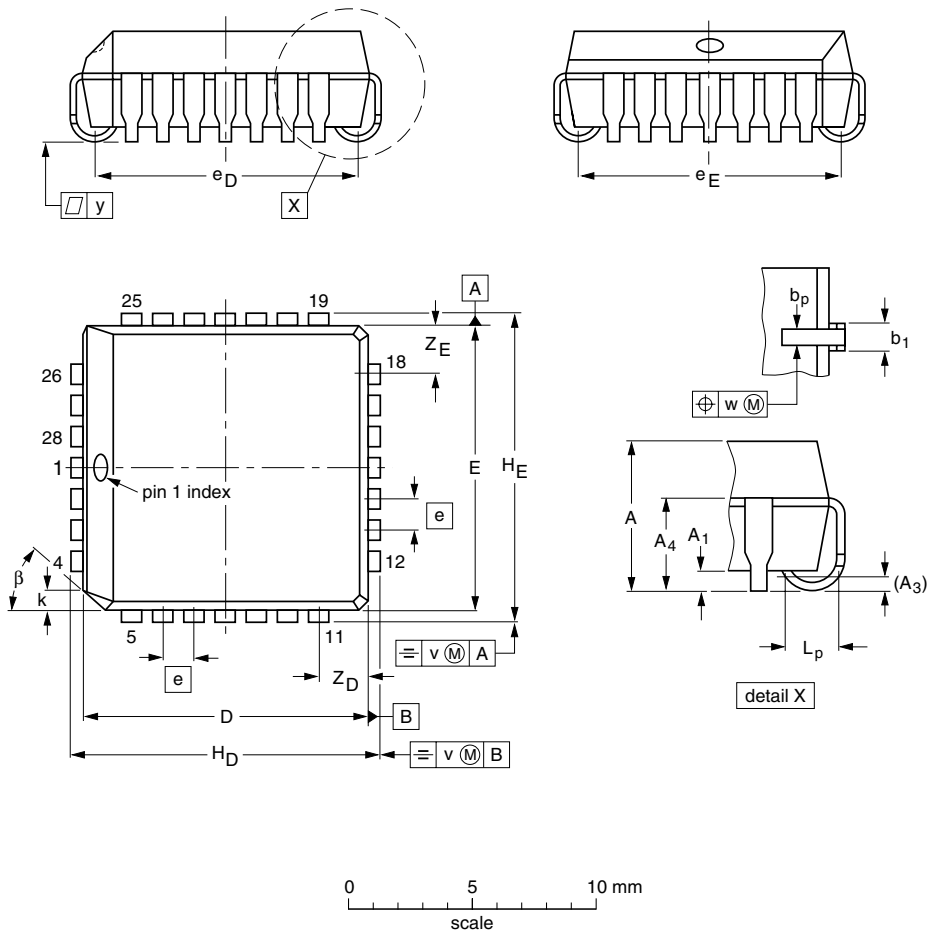
Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT361-1		MO-153				~~99-12-27~~ 03-02-19

Fig 29. Package outline SOT361-1 (TSSOP28)

PLCC28: plastic leaded chip carrier; 28 leads **SOT261-2**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	11.58 11.43	11.58 11.43	1.27	10.92 9.91	10.92 9.91	12.57 12.32	12.57 12.32	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.456 0.450	0.456 0.450	0.05	0.43 0.39	0.43 0.39	0.495 0.485	0.495 0.485	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT261-2	112E08	MS-018	EDR-7319			~~99-12-27~~ 01-11-15

Fig 30. Package outline SOT261-2 (PLCC28)

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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